SEMPrep2

High-quality and site-specific sample preparation for SEM application



- Cross-sectional sample preparation by slope cutting in 90° and 30° angles using dedicated sample holders
- Final polishing and cleaning of traditional SEM and EBSD samples
- Load-lock system for faster, easier and safer sample exchange
- High-energy ion gun for rapid milling and low-energy ion gun for gentle surface polishing and cleaning
- Optional ultra-high-energy ion gun, recommended for ion milling of extra hard materials and for extreme fast milling
- Automated parameter settings and operation
- Sample rotation and oscillation
- Real-time monitoring of the milling process by high-resolution CMOS camera and TFT monitor

DESCRIPTION

The SC-2100 model is equipped with both high- and low-energy ion sources. Rapid slope cutting with the high-energy ion gun provides cross-sectional SEM samples for semiconductor industry, material sciences, geology and other scientific and industrial purposes. The system also delivers a solution to improve and clean mechanically polished SEM samples and to prepare damage-free surfaces for EBSD measurements. The new 16 keV ultra-high-energy ion source is more powerful and has a higher sputtering rate than before. For the most gentle surface treatment of the delicate samples, the low-energy ion source is also available.

SPECIFICATIONS

• Ion sources Two ion guns: - high-energy ion gun operating up to 10 keV or

ultra-high-energy ion gun operating up to 16 keV (optional)

- low-energy ion gun in the range of 100 eV to 2 keV

continuously and independently adjustable milling energy

• Sample stage Sample size: slope cutting sample holder (available with 30° and 90° tilted platforms)

for 30° holder: max. 42 mm (l) x 16 mm (w) x 5.5 mm (th)

for 90° holder: max. 20 mm (l) x 16 mm (w) x 7.0 mm (th)

sample holder for surface cleaning using 3 different head types:

flat head type: max. Ø33,5 mm x 8 mm standard type: max. Ø33,5 mm x 9 mm hollow type 1: max. Ø26 mm x 21 mm hollow type 2: max. Ø32 mm x 19,5 mm

Sample tilting: 0° to 30° in 0.1° increments

Sample rotation: in-plane rotation, 360°

Sample oscillation: in-plane oscillation from $\pm 10^{\circ}$ to $\pm 120^{\circ}$ in 5° steps

Sample cooling
LN₂ cooling to prepare heat-sensitive samples (optional)

Peltier cooling to protect the samples from thermal overrun (optional)

Vacuum system
Oil-free diaphragm and turbomolecular pumps with combined (Pirani/Penning) vacuum gauge

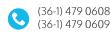
• Gas supply system 99.999% purity argon

High-precision working gas flow control

• Imaging system High-resolution CMOS camera with fix zoom

• Computer control Easy-to-use graphical interface, automated ion source setup, milling parameter setting and

operation control

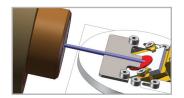




APPLICATIONS

ION BEAM SLOPE CUTTING

To produce excellent quality planar cross-sections of different solid state materials for SEM/EBSD imaging and microanalysis.

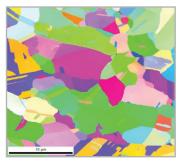




Sn-Ag solder ball grid array (BGA)



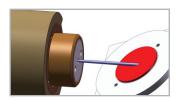
Metal wire bonding



EBSD image (OIM) made on an as-cut surface of copper

FINAL POLISHING

To produce samples for Electron Backscatter Diffraction (EBSD) study and Orientation Imaging Microscopy (OIM).





Copper



Nickel



Martensitic steel



Limestone







